

ABSTRACT

A probe apparatus for preferably testing packaged circuit chips combines an ACE with plunger pins placed in between the ACE and the test contact. A plunger pin provides a contact end for contacting the test contacts and a back end configured for indenting the ACE. The contact end may be configured in conjunction with the test contacts particularities whereas the plunger pins' back ends have a curvature that corresponds to the ACE's deformation behavior in the impinging vicinity such wear relevant ACE deformations are kept to a minimum. The plunger pins are arrayed in a removable frame. For contacting ball grid arrays, the plunger pins feature on their front ends self centering interacting concentrically arrayed crown peaks.